### **Philips Semiconductors**

**Product specification** 

# Damper-Modulator fast, high-voltage

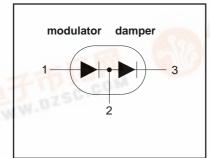
BYM358DX

# **FEATURES**

- Low forward volt drop
- Ultra fast switching
- Soft recovery characteristic
- High thermal cycling performance
- Isolated mounting tab

# SYMBOL

WWW.DZSC



# **QUICK REFERENCE DATA**

1	DAMPER	MODULATOR
	V <sub>R</sub> =1500 V	V <sub>R</sub> =600 V
	V <sub>F</sub> ≤ 1.5 V	$V_F \le 1.08 \text{ V}$
	I <sub>F(peak)</sub> =7 A	$I_{F(peak)} = 7 A$
	I <sub>FSM</sub> ≤ 66 A	$I_{FSM} \le 70 \text{ A}$
	t <sub></sub> ≤ 170 ns	t <sub>rr</sub> ≤ 60 ns

# **GENERAL DESCRIPTION**

Combined damper and modulator diodes in an isolated plastic envelope for horizontal deflection in PC monitors.

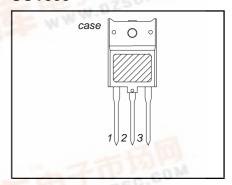
The BYM358DX contains diodes with performance characteristics designed specifically for applications from 32kHz to 120kHz

The BYM358DX series is supplied in the conventional leaded SOT399 package.

### **PINNING**

PIN	DESCRIPTION
1	modulator anode
2	common anode/cathode
3	damper cathode

### **SOT399**



### LIMITING VALUES

 $T_i = 25$  °C unless otherwise stated

		The state of the s	DAM	PER	MODU	LATOR	
SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	MIN	MAX	UNIT
V <sub>RSM</sub>	Peak non-repetitive reverse voltage.		-	1500	-	600	V
V <sub>RRM</sub>	Peak repetitive reverse voltage		-	1500	-	600	V
V <sub>RWM</sub>	Crest working reverse voltage		-	1300	工祇	600	V
I <sub>F(peak)</sub>	Peak forward current	31-70 kHz monitor.	· it	7	W.OZ	s 07 0 °	Α
I <sub>F(RMS)</sub>	RMS forward current	sinusoidal;a=1.57	415	15.7	-	14.1	Α
I <sub>FSM</sub>	Peak non-repetitive forward current	t = 10 ms t = 8.3 ms sinusoidal;with reapplied V <sub>RWM(MAX)</sub>	-	60 66	- -	70 77	A A
T <sub>stg</sub>	Storage temperature Operating junction temperature		-40 -	150 150	-40 -	150 150	ů Ů



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# **ISOLATION LIMITING VALUE & CHARACTERISTIC**

T<sub>hs</sub> = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>isol</sub>	Repetitive peak voltage from all three terminals to external heatsink	R.H. ≤ 65 % ; clean and dustfree	-	-	2500	V
C <sub>isol</sub>	Capacitance from T2 to external heatsink	f = 1 MHz	-	22	-	pF

# THERMAL RESISTANCES

			DAM	IPER	MODU	LATOR	
SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	TYP.	MAX.	UNIT
R <sub>th j-hs</sub>	Thermal resistance junction to heatsink	with heatsink compound	-	3.5	-	4	K/W
R <sub>th j-a</sub>	Thermal resistance junction to ambient	in free air.	35	-	35	-	K/W

# STATIC CHARACTERISTICS OF DAMPER

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	TYP	MAX.	UNIT
V <sub>F</sub>	Forward voltage Reverse current	$I_F = 6.5 \text{ A}$ $I_F = 6.5 \text{ A}$ ; $T_j = 125^{\circ}\text{C}$ $V_R = V_{RWM}$	1.3 1.2 10 300	1.6 1.5 100 500	V V μΑ μΑ
		$V_R = V_{RWM}$ $T_j = 100$ °C	300	300	μΑ

# STATIC CHARACTERISTICS OF MODULATOR

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	TYP	MAX.	UNIT
V <sub>F</sub>	Forward voltage  Reverse current.	$I_F = 8 \text{ A}$ $I_F = 8 \text{ A}$ ; $T_j = 150^{\circ}\text{C}$ $I_F = 20 \text{ A}$ $V_R = V_{RWM}$	1.2 0.95 1.3 10	1.3 1.08 1.45 50	V V μΑ
		$ \begin{vmatrix} V_R = V_{RWM} \\ T_j = 100  ^{\circ}C \end{vmatrix} $	100	350	μΑ

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# **ELECTRICAL CHARACTERISTICS OF DAMPER**

T<sub>i</sub> = 25 °C unless otherwise stated

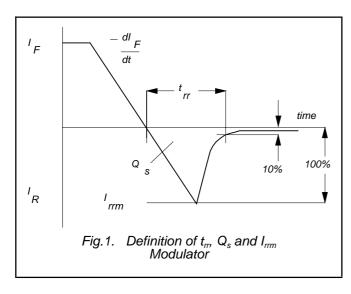
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SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
t <sub>rr</sub>	Reverse recovery time	$I_F = 1 \text{ A}; V_R \ge 30 \text{ V};$	130	170	ns
$egin{pmatrix} Q_s \ V_{fr} \ \end{pmatrix}$	Reverse recovery charge Peak forward recovery voltage	-dI <sub>F</sub> /dt = 50 A/μs 2 A,30 V,20 A/μs I <sub>F</sub> = 6.5 A; dI <sub>F</sub> /dt = 50 A/μs	0.65 29	0.9	μC V

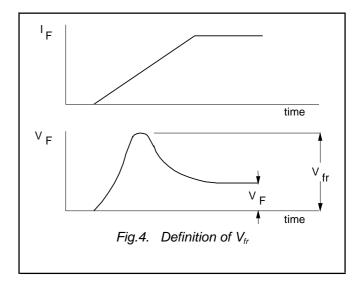
# **ELECTRICAL CHARACTERISTICS OF MODULATOR**

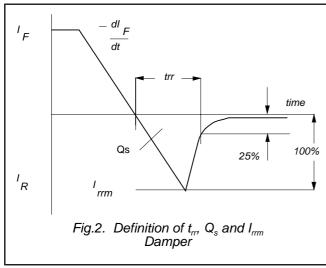
T<sub>i</sub> = 25 °C unless otherwise stated

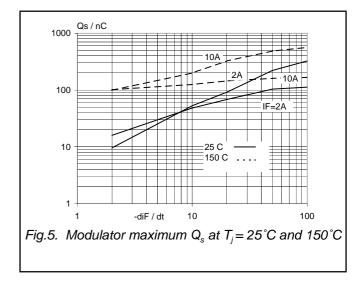
SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
t <sub>rr</sub>	Reverse recovery time	$I_F = 1 \text{ A}; V_R \ge 30 \text{ V};$ - $dI_F/dt = 100 \text{ A}/\mu\text{s}$	35	60	ns
I <sub>rrm</sub>	Peak reverse recovery current	$I_F = 10 \text{ A to } V_R \ge 30 \text{ V};$ $dI_F/dt = 50 \text{ A/}\mu\text{s}; T_i = 100^{\circ}\text{C}$	3.0	5.5	Α
$egin{array}{c} Q_s \ V_{fr} \end{array}$	Reverse recovery charge Peak forward recovery voltage	2 A,30 V,20 A/μs I <sub>F</sub> = 10 A; dI <sub>F</sub> /dt = 10 A/μs	40 5.0	70 -	nC V

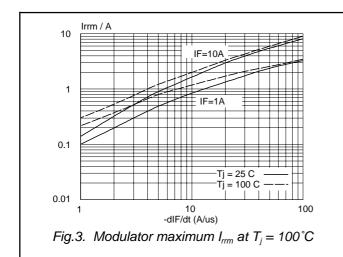
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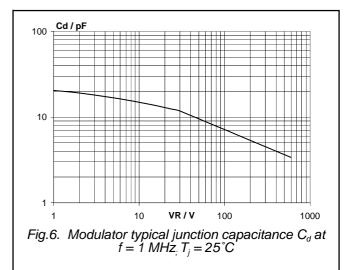












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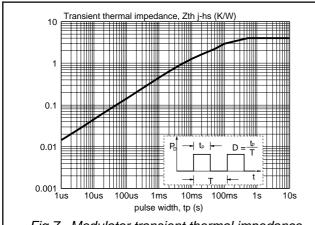


Fig.7. Modulator transient thermal impedance  $Z_{th} = f(t_p)$ 

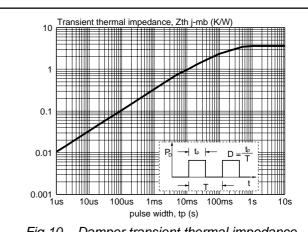


Fig. 10. Damper transient thermal impedance  $Z_{th} = f(t_p)$ 

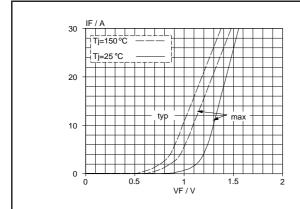


Fig.8. Modulator typical and maximum forward characteristic;  $I_F = f(V_F)$ ; parameter  $T_i$ 

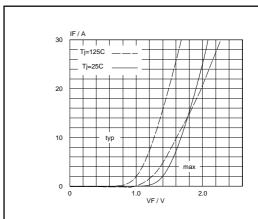


Fig.11. Damper forward characteristic  $I_F = f(V_F)$ ; parameter  $T_i$ 

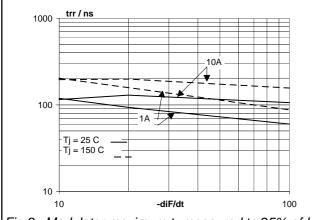
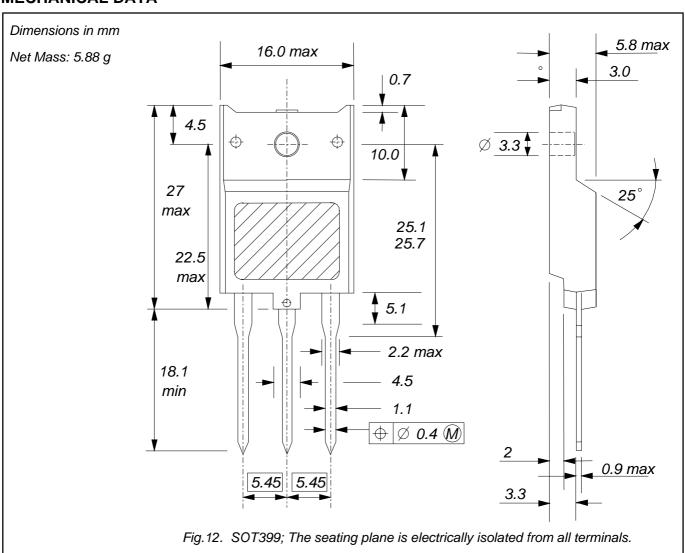


Fig.9. Modulator maximum  $t_{rr}$  measured to 25% of  $I_{rm}$ ;  $T_j = 25^{\circ}\text{C}$  and 150  $^{\circ}\text{C}$ 

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# **MECHANICAL DATA**



- Refer to mounting instructions for F-pack envelopes.
   Epoxy meets UL94 V0 at 1/8".

BYM358DX

### **DEFINITIONS**

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				

#### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

# **Application information**

Where application information is given, it is advisory and does not form part of the specification.

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